

Description

The IPD068P03L3G uses advanced trench technology

to provide excellent $R_{\text{DS}(\text{ON})},$ low gate charge and

operation with gate voltages as low as 4.5V. This

device is suitable for use as a

Battery protection or in other Switching application.

General Features

V_{DS} = -30V I_D =-80 A

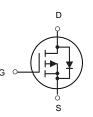
 $R_{DS(ON)} < 8.8 \, m\Omega @ V_{GS} = 10V$

Application

Battery protection

Load switch Uninterruptible power supply





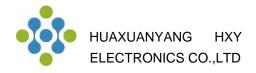
P-Channel MOSFET

Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
IPD068P03L3G	TO252-2L	80P03 XXX YYYY	2500

Absolute Maximum Ratings (Tc=25°Cunless otherwise noted)

Symbol	Parameter	Rating	Units	
VDS	Drain-Source Voltage	-30	V	
Vgs	Gate-Source Voltage	±25	V	
I₀@Tc=25°C	Continuous Drain Current, V _{GS} @ -10V ¹	ous Drain Current, V _{GS} @ -10V ¹ -80		
I⊳@Tc=100°C	Continuous Drain Current, V _{GS} @ -10V ¹	-42	А	
Ідм	Pulsed Drain Current ²	-172	А	
EAS	Single Pulse Avalanche Energy ³	31	mJ	
las	Avalanche Current	-25	А	
P _D @T _C =25°C	Total Power Dissipation ⁴	31.2	W	
P _D @T _A =25°C	Total Power Dissipation ⁴	2	W	
Тѕтс	Storage Temperature Range	-55 to 150	°C	
TJ	Operating Junction Temperature Range	-55 to 150	°C	
Reja	Thermal Resistance Junction-Ambient ¹	43	°C/W	
Rejc	Thermal Resistance Junction-Case ¹	4	°C/W	



Electrical Characteristics T_c = 25°C, unless otherwise noted

Parameter		Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static Characteristics		1		1	1	1		
Drain-Source Breakdown V	oltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = -250µA	-30	-	-	V	
Gate-body Leakage curren	t	lgss	V _{DS} = 0V, V _{GS} = ±20V	-	-	±100	nA	
Zero Gate Voltage Drain	TJ=25℃	- Idss		-	-	-1	μA	
Current	TJ=52℃		$V_{DS} = -24V, V_{GS} = 0V$	-	-	-5		
Gate-Threshold Voltage		V _{GS(th)}	V_{DS} = V_{GS} , I_D = -250 μ A	-1.0	-1.6	-2.5	V	
Desia Osuras On Desistan	- 2		V _{GS} = -10V, I _D = -12A	-	5.5	8.8		
Drain-Source On-Resistance	;e-	R _{DS(on)}	V _{GS} = -4.5V, I _D = -8A	-	9	14	14 mΩ	
Forward Transconductance		g fs	V _{DS} = -5V, I _D = -20A	-	28	-	S	
Dynamic Characteristic	cs			•	•	•	•	
Input Capacitance		Ciss		-	4320	-		
Output Capacitance Reverse Transfer Capacitance		Coss	V _{DS} = -15V, V _{GS} =0V, f =1MHz	-	529	-	pF	
		Crss		-	487	-		
Switching Characterist	ics			•		•		
Gate Resistance		Rg	V_{DS} = 0V, V_{GS} = 0V, f=1.0MHz	-	4.0	-	Ω	
Total Gate Charge		Qg		-	45	-		
Gate-Source Charge		Qgs	V _{GS} = -10V, V _{DS} = -15V, I _D = -15A	-	8.5	-	nC	
Gate-Drain Charge		Q _{gd}		-	12.8	-		
Turn-On Delay Time		t _{d(on)}		-	18.9	-		
Rise Time		tr	- V _{GS} = -10V, V _{DD} = -15V,	-	15.7	-	nS	
Turn-Off Delay Time		t _{d(off)}	$R_{\rm G} = 2.5\Omega, I_{\rm D} = -15A$	-	64.8	-		
Fall Time		tr		-	36.5	-		
Drain-Source Body Dic	de Charac	teristics	1	I	1	1	1	
Diode Forward Voltage ²		V _{SD}	I _S = -1A, V _{GS} = 0V	-	-	-1	V	
Continuous Source Current ^{1,5}		ls	V _G =V _D =0V , Force Current	_	_	-80	Α	

Note :

1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.

2.The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%

3. The EAS data shows Max. rating . The test condition is V_DD= -25V, V_GS= -10V, L= 0.1mH, I_{AS}= -25A

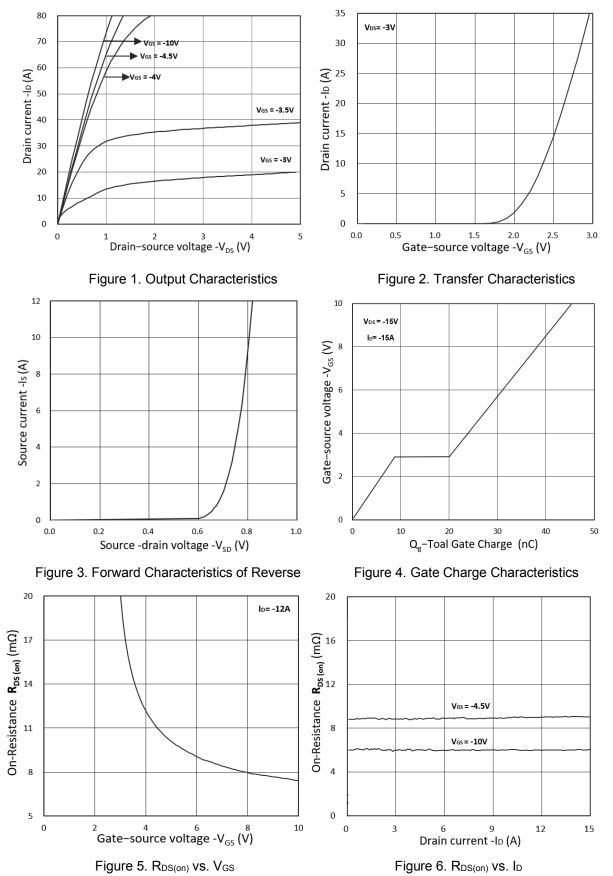
4.The power dissipation is limited by 150°C junction temperature

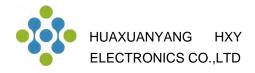
5. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.



IPD068P03L3G P-Channel Enhancement Mode MOSFET

Typical Characteristics





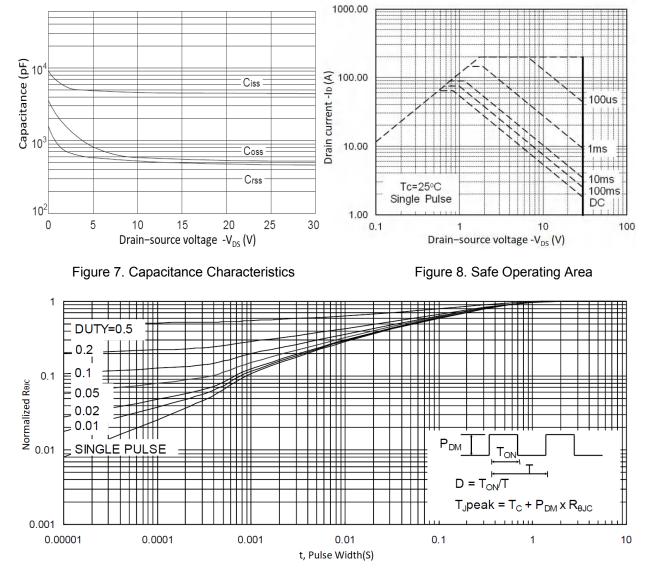


Figure 9. Normalized Maximum Transient Thermal Impedance

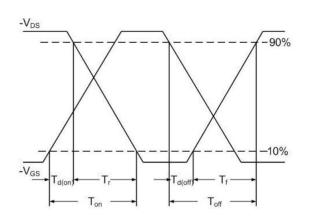
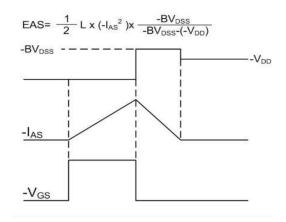
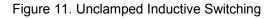


Figure 10. Switching Time Waveform

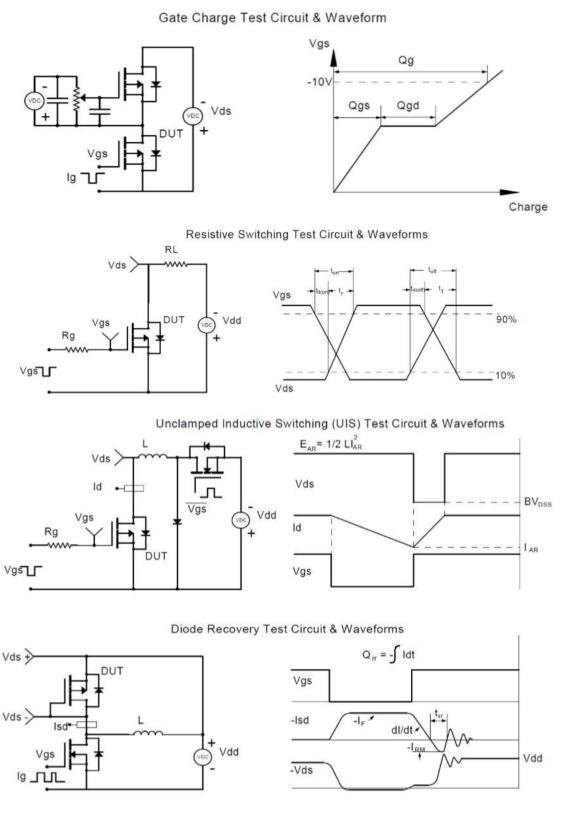




Waveform

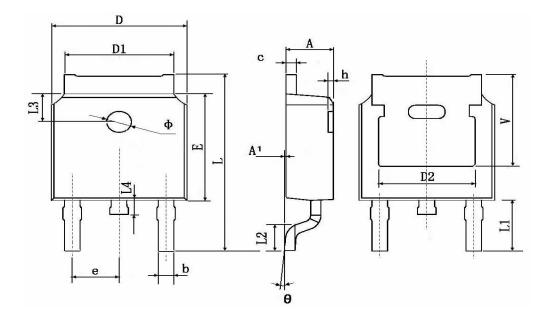


Test Circuit





TO252-2L Package Information



	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
A	2.200	2.400	0.087	0.094	
A1	0.000	0.127	0.000	0.005	
b	0.660	0.860	0.026	0.034	
С	0.460	0.580	0.018	0.023	
D	6.500	6.700	0.256	0.264	
D1	5.100	5.460	0.201	0.215	
D2	4.830	D TYP.	0.190 TYP.		
E	6.000	6.200	0.236	0.244	
е	2.186	2.386	0.086	0.094	
L	9.800	10.400	0.386	0.409	
L1	2.900 TYP.		0.114 TYP.		
L2	1.400	1.700	0.055	0.067	
L3		D TYP.	0.063 TYP.		
L4	0.600	1.000	0.024	0.039	
Φ	1.100	1.300	0.043	0.051	
θ	0 °	8°	0°	8°	
h	0.000	0.300	0.000	0.012	
V	5.350	D TYP.	0.211 TYP.		



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